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FEB 10 2003

January 30, 2663 NOLOGY CENTER 2800

**Box NON-FEE AMENDMENT** Commissioner For Patents Washington, D.C. 20231

Application No.: First Inventor:

09/895,501

**Donald Craig Foster** 

Confirmation No.:

7243

Group Art Unit:

Filing Date: Examiner:

June 29, 2001 David E. Graybill

Atty. Docket No.:

2827

M-11315 US

Title:

Leadframe Having Fine Pitch Bond Fingers Formed Using Laser Cutting Method

Assignee:

Amkor Technology, Inc.

Dear Sir:

Transmitted herewith are the following documents in the above-identified application:

(1) Return Receipt Postcard;

(2) This Transmittal Letter (in duplicate);

(3) Response to Office Acton Mailed 1/17/03 (2 pp.).

The fee has been calculated as shown below:  $\boxtimes$ 

## **CLAIMS AS AMENDED**

	Claims Remainin After Amendment		Highest No. Previously <u>Paid For</u>		Present Extra		<u>Rate</u>		Additional Fee
Total Claim	s 34	Minus	41	=	0	x	\$18.00	\$	0.00
	endent	Minus	5	=	0	х	\$84.00	\$_	0.00
Fee of \$ for the first filing of one or more multiple dependent claims								\$	
Fee for Request for Extension of Time ( month(s))								\$	
市	Fee for								
	Total additional fee for	this Amendmer	nt:					\$	0.00
☐ Please charge our Deposit Account No. 19-2386 in the amount of								\$	0.00
	Commissioner is authorized to deduct the necessary fee from Deposit Account No. 19-2386.								
Also, charge any additional fees required and credit any overpayment to our Deposit Account No. 19-2386.									

EXPRESS MAIL LABEL NO:

EV 160 615 980 US

Respectfully submitted,

James E. Parsons Attorney for Applicants Reg. No. 34,691

914780



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Assignee:

Amkor Technology, Inc.

San Jose, California January 30, 2003

**BOX NON-FEE AMENDMENT** COMMISSIONER FOR PATENTS Washington, D. C. 20231

## **RESPONSE TO OFFICE ACTION MAILED 1/17/03**

Dear Sir:

The following amendments and remarks are in reply to the Office Action dated January 27, 2003.

## IN THE SPECIFICATION

Please add the following paragraph to the Specification at page 3, between paragraphs 14 and 15.

FIG. 7 is a plan view of a portion of a leadframe with a second alternative bond finger shape.

-1-

LAW OFFICES OF SKJERVEN MORGILL LLP San Jose, CA San Francisco, CA